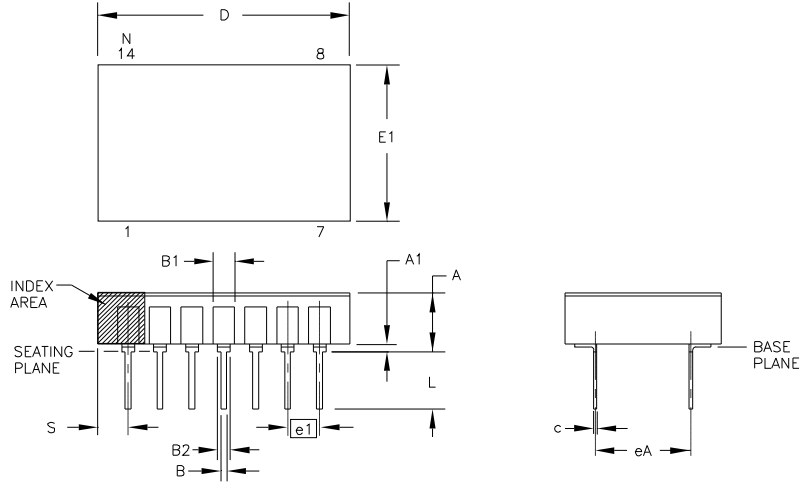


Package Number 148 - 14-Lead Bottom Braze DIP, .300 Wide



DIM	INCHES		MILLIMETERS		NOTE	DIM	INCHES		MILLIMETERS		NOTE
	MIN.	MAX.	MIN.	MAX.			MIN.	MAX.	MIN.	MAX.	
A	.155	.215	3.94	5.46							
A1	.015	.035	0.38	0.89							
B	.016	.020	0.41	0.51							
B1	.045	.055	1.14	1.40							
B2	.035	.045	0.89	1.14							
c	.009	.012	0.23	0.30							
D	.770	.810	19.56	20.57							
E1	.480	.500	12.19	12.70							
e1	.100	BASIC	2.54	BASIC							
eA	.290	.310	7.37	7.87							
L	.150	.210	3.81	5.33							
N	14		14								
S	.080	.110	2.03	2.79							

- NOTES:
- LEADS IN TRUE POSITION WITHIN .010" (0.25mm) R @ MMC AT SEATING PLANE.
 - PIN NUMBERS SHOWN FOR REFERENCE ONLY. NUMBERS MAY NOT BE MARKED ON PACKAGE.
 - A VISUAL INDEX FEATURE MUST BE LOCATED WITHIN THE CROSS-HATCHED AREA.

PACKAGE NUMBER: ZZ148 REV.: A
 JEDEC NUMBER: NONE

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